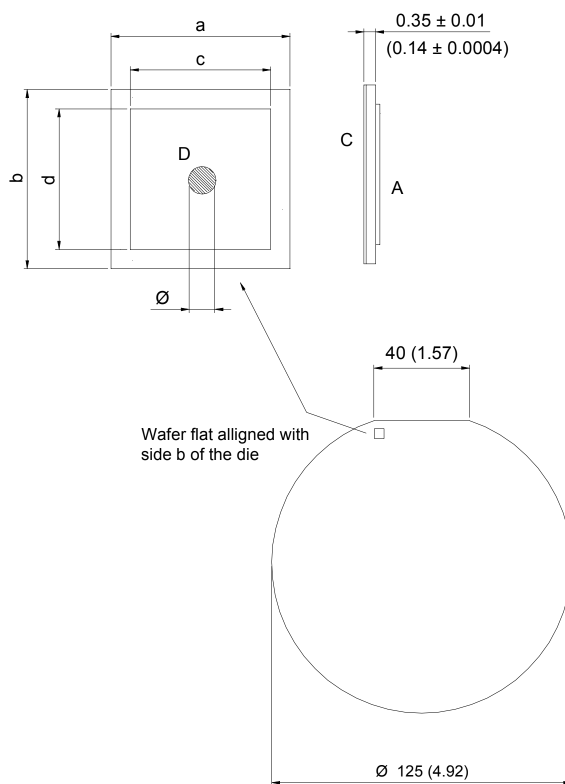
International
IOR Rectifier

Bulletin I0505J rev. B 10/00

SC200.....5. Series

SCHOTTKY DIE 200 x 200 mils



NOTES:

1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS (INCHES).

2. CONTROLLING DIMENSION: (INCH).

3. DIMENSIONS AND TOLERANCES:
   a = 5.08 + 0, - 0.05
   (0.200 + 0, - 0.002)
   b = 5.08 + 0, - 0.05
   (0.200 + 0, - 0.002)
   c = 4.57 + 0, - 0.003
   (0.180 + 0, - 0.0001)
   d = 4.57 + 0, - 0.003
   (0.180 + 0, - 0.0001)
   Ø = 0.7 ± 0.1
   (0.03 ± 0.004)

4. LETTER DESIGNATION:
   A = Anode (Top Metal)
   C = Cathode (Back Metal)
   D = Reject Ink Dot (only on non-conforming dies)

5. SAWING:
   Recommended Blade
   SEMITEC S1025 QS00 Blade

NOT TO SCALE

NOTE: 10 mils die thickness is available on specific request only.
Contact factory for information.

Electrical Characteristics

Device #	T_J Max. (°C)	V_R (V)	Typ. I_R @ 25°C (µA)	Typ. I_R @ 125°C (mA)	Max. V_F @ I_F (V)	Package Style
SC200**R**015x5x	125	15	7500	900	0.45 @ 80A	D-61
SC200**S**020x5x	150	20	1200	450	0.51 @ 80A	D-61
SC200**S**030x5x	150	30	600	270	0.55 @ 80A	D-61
SC200**S**045x5x	150	45	400	210	0.66 @ 80A	D-61
SC200**S**060x5x	150	60	n.a. contact factory			
SC200**H**045x5x	175	45	70	26	0.74 @ 80A	D-61
SC200**H**100x5x	175	100	30	18	0.89 @ 60A	D-61
SC200**H**150x5x	175	150	15	10	1.14 @ 80A	D-61

Mechanical Data

Device #		Metal Thickness Front Metal			Metal Thickness Back Metal		
SC200xxxx**A**5x	Wire Bondable	–	Al 30 kÅ	–	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ
SC200xxxx**S**5x	Solderable	Ti 2 kÅ	Ni 1 kÅ	Ag 35 kÅ	Cr 1 kÅ	Ni 2 kÅ	Ag 3 kÅ

Recommended Storage Environment: Store in original container, in dessicated nitrogen, with no contamination.
Shelf life for parts stored in above condition is 2 years.
If the storage is done in normal atmosphere shelf life is reduced to six months.

Packaging

Device #	Description	Minimum Order Quantity Die in Sale Package
SC200xxxxx5**B**	Inked Probed Unsawn Wafer (Wafer in Box)	350
SC200xxxxx5**R**	Probed Die in Tape & Reel	8,000
SC200xxxxx5**P**	Probed Die in Waffle Pack	350
SC200xxxxx5**F**	Inked Probed Sawn Wafer on Film	350

Ordering Information Table

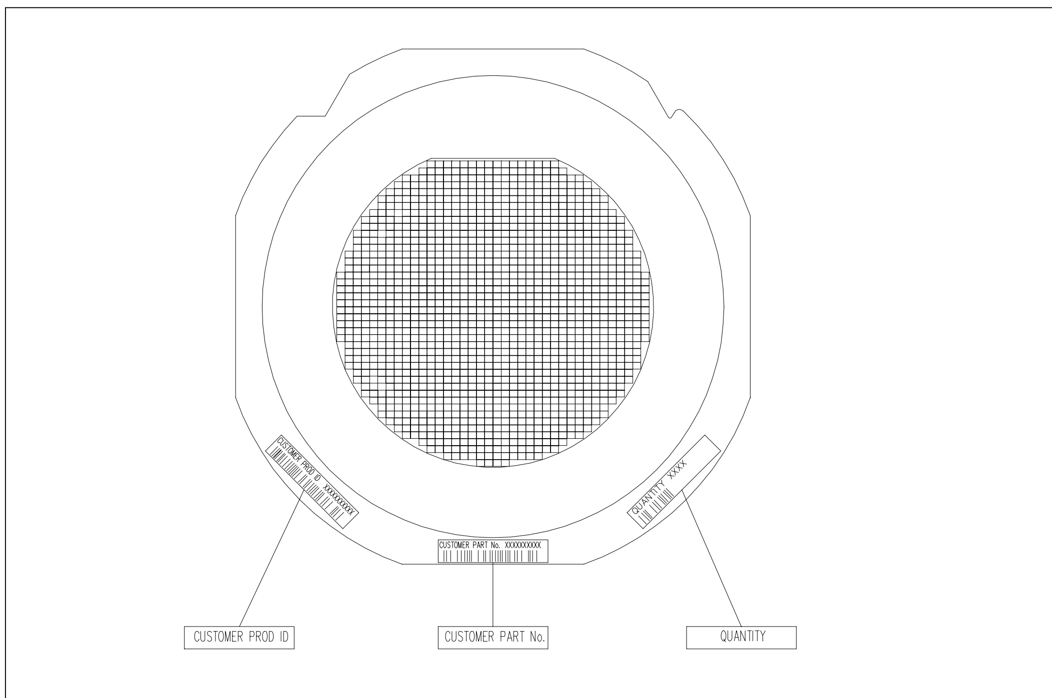
Device Code

SC	200	S	100	A	5	B
1	2	3	4	5	6	7

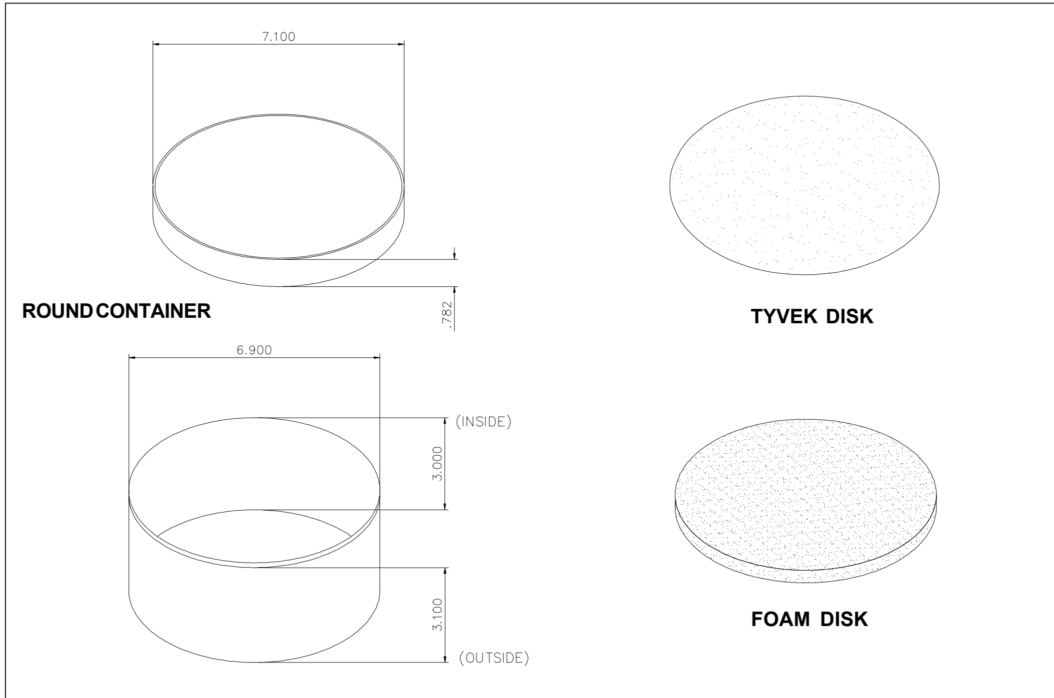
1 - Schottky Die
2 - Chip Dimension in Mils
3 - Process (see Electrical Characteristics Table)
4 - Voltage code: Code = V_{RRM}
5 - Chip surface metallization (see Mechanical Data Table)
6 - Wafer Diameter in inches
7 - Packaging (see Packaging Table)

H = 830 Process
R = OR'ing Process
S = Standard Process

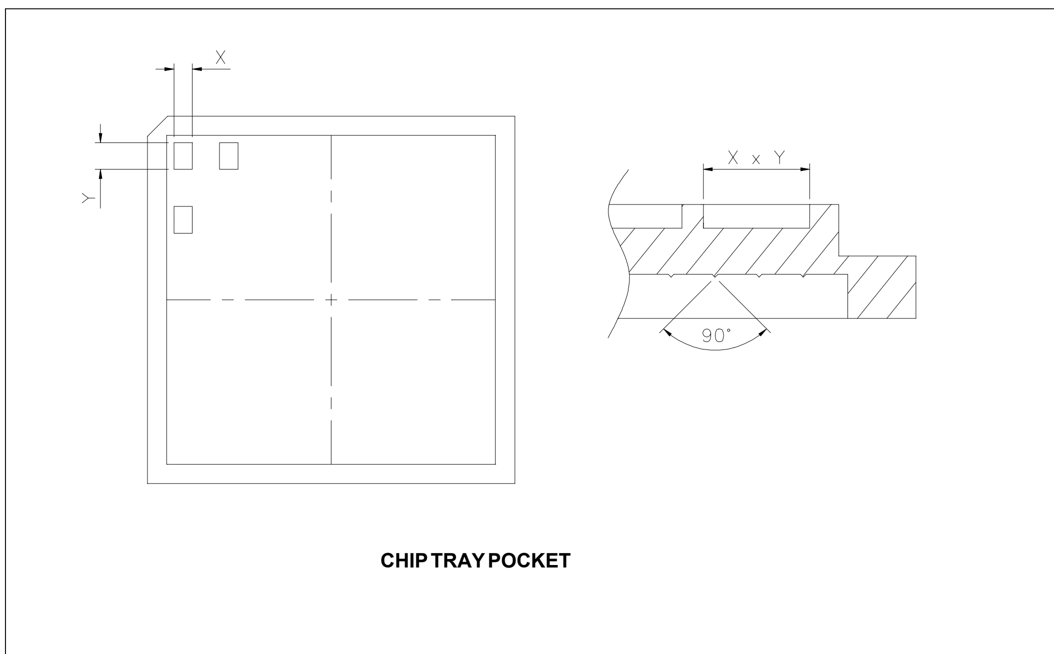
Wafer on Film



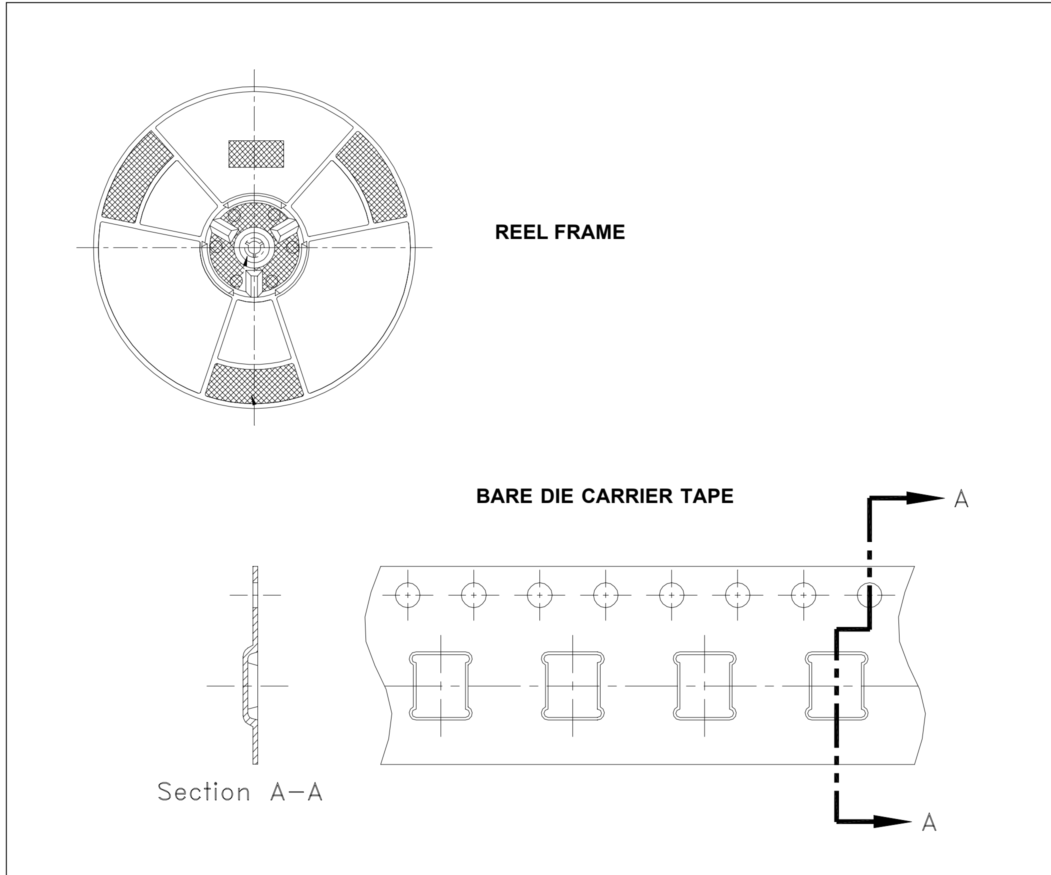
Wafer in Box



Die in Waffle Pack



Tape and Reel



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IR FAR EAST: K&H Bldg., 2F, 30-4 Nishi-Ikebukuro 3-Chome, Toshima-Ku, Tokyo, Japan 171. Tel: 81 3 3983 0086.
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